FRAME FOR SEMICONDUCTOR PACKAGE

ABSTRACT OF THE DISCLOSURE

Frame F comprises plural lead frames 10 arranged through grid-leads L in matrix. Semiconductor devices are mounted on individual lead frames 10 of frame F, respectively and collectively molded with molding compound. Thereafter, the collectively molded semiconductor devices are cut at grid-leads L by means of dicing saw so that individual semiconductor packages are obtained. The frame F further has groove portions. The groove portions are formed by half-cutting by etching a metal of frame F from the front or back at areas corresponding to grid-leads, so that grid-frames are made thin. When a width of groove portions is larger than a width of dicing saw, cut burrs are reduced. When a width of groove portions is smaller than a width of dicing saw, the occurrence of metal powder dusts is restrained and time required for cutting becomes smaller.

This Sheet Has Been Replaced

